

CLIPPEDIMAGE= JP407090239A
PAT-NO: JP407090239A
DOCUMENT-IDENTIFIER: JP 07090239 A
TITLE: ELECTRICALLY CONDUCTIVE RESIN PASTE

PUBN-DATE: April 4, 1995

INVENTOR-INFORMATION:

NAME

OKUBO, HIKARI

KOBAYASHI, MICHIO

ASSIGNEE-INFORMATION:

NAME

SUMITOMO BAKELITE CO LTD

COUNTRY

N/A

APPL-NO: JP05239285

APPL-DATE: September 27, 1993

INT-CL_(IPC): C09J163/00; C08G059/24 ; H01B001/20

ABSTRACT:

PURPOSE: To provide an electrically conductive resin paste composed of respective specific epoxy compound, hydroxyl-containing compound and silver powder at specific ratios, having excellent coating workability and low water-absorption, providing a cured product having low elastic modulus and free from cracking and useful for bonding a semiconductor element to a metal frame, etc.

CONSTITUTION: This electrically conductive resin paste contains, as essential components, (A) 60-85wt.% of silver powder, (B) 3-20wt.% of an epoxy compound having naphthalene skeleton and expressed by the formula I (R<SB>1</SB> and R<SB>2</SB> are glycidyl ether group or H and at least one of R<SB>1</SB> and R<SB>2</SB> is glycidyl ether group; (n) is 0 or 1), e.g 1,6-dihydroxynaphthalene diglycidyl ether and (C) 0.1-20wt.% of a compound

having two phenolic hydroxyl groups in one molecule.

COPYRIGHT: (C)1995, JPO